



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



- ▶ NCSP CHIP LED
- ▶ 2030 0.9t Series
- ▶ Cool White (5800K) / Blue (465nm)

N0D53S29



Release Date: 25 November 2021 Version: A1.1



2030 0.9t Series

RoHS Compliant



FEATURES:

- **Package:** Ceramic High Power CSP Package
- **Forward Current:** 350~700mA per colour
- **Forward Voltage (typ.):** 3/3V*
- **Luminous Flux (typ.):** 160/45lm@350mA
- **Colour:** Cool White/Blue
- **CCT/Colour Temperature (typ.):** 5800K/465nm
- **Viewing angle:** 120°
- **Materials:**
 - Die: Flip-Chip InGaN
 - Resin: Silicon (Yellow Diffused)
 - L/T Finish: Au plated AlN
- **Operating Temperature:** -40~+125°C
- **Storage Temperature:** -40~+125°C
- **Grouping parameters:**
 - Forward Voltage
 - Luminous Flux
 - CIE Chromaticity
- **Soldering methods:** IR Reflow
- **Preconditioning:** MSL2 according to J-STD020
- **Packing:** 8mm tape with Max.2000pcs /reel, ø180mm (7")

* in order of Cool White/Blue

APPLICATIONS:

- Decorative Lighting
- Portable Lighting
- Outdoor Lighting
- Commercial Lighting
- Indoor Lighting
- Industrial Lighting
- Automotive Lighting

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	350/350*	mA
Maximum Forward Current	I _{MAX}	700/700	mA
Junction Temperature	T _j	150	°C
Thermal Resistance Junction to Solder Point	R _{th(j-s)}	10	K/W
Radiating Surface	---	1.44	mm ²
Operating Temperature	T _{OPR}	-40~+125	°C
Storage Temperature	T _{STG}	-40~+125	°C

* in order of Cool White/Blue

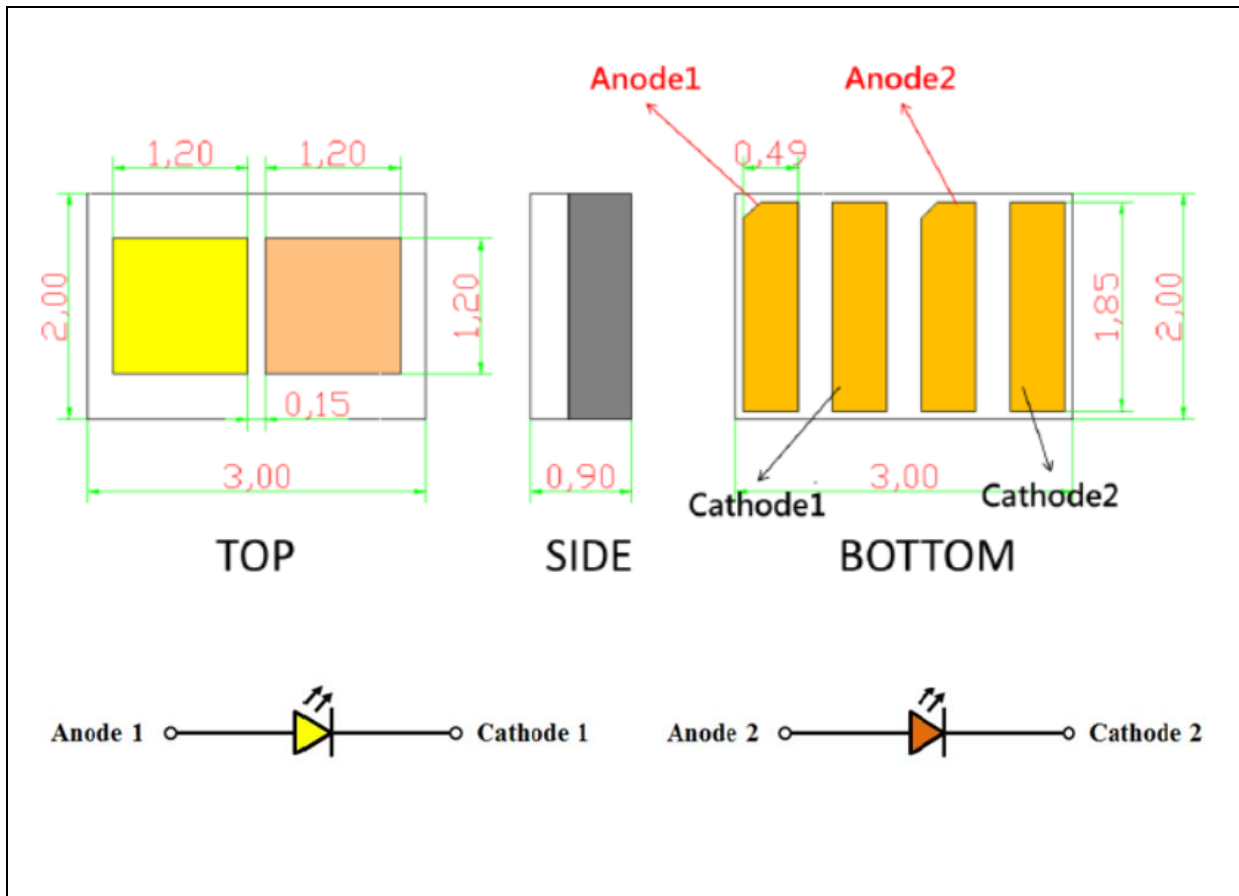
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.9/2.9*	3.0/3.0	3.2/3.2	V	I _F =350mA
Luminous Flux	Φ _v	140/30	---/---	180/60	lm	I _F =350mA
Cool White CCT	---	5200	5800	6500	K	I _F =350mA
Blue Wavelength	λ _D	460	---	470	nm	I _F =350mA
Viewing Angle	2θ _{1/2}	---	120	---	deg	I _F =350mA

- Luminous flux (Φ_v) ±7%, Forward Voltage (V_F) ±0.05V, Viewing angle(2θ_{1/2}) ±10°, CRI ±2
- * in order of Cool White/Blue

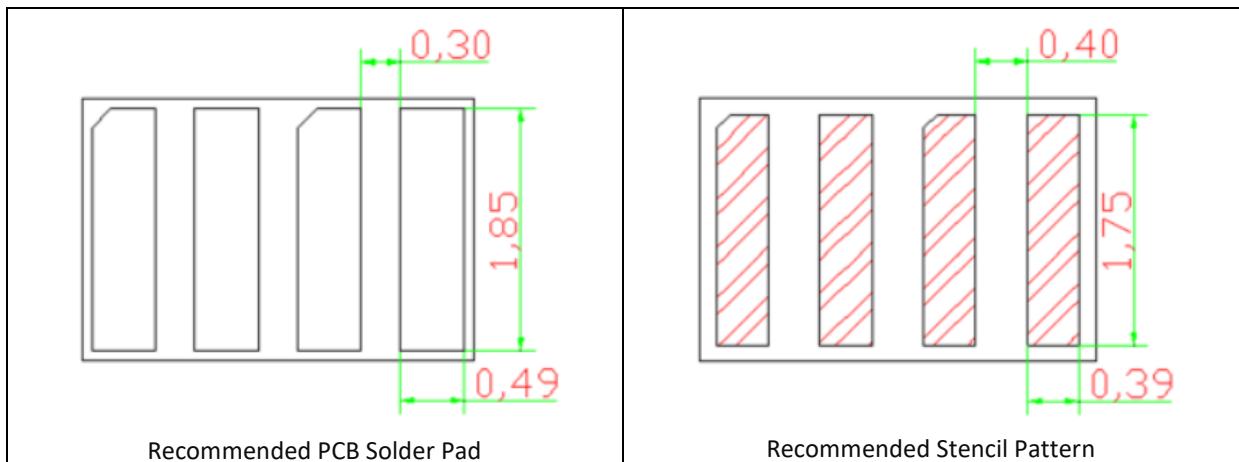
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance $\pm 0.13\text{mm}$, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance $\pm 0.12\text{mm}$ with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 350\text{mA}$):

Code		Min.	Max.	Unit
□	Cool White	2.9	3.2	V
	Blue	2.9	3.2	V

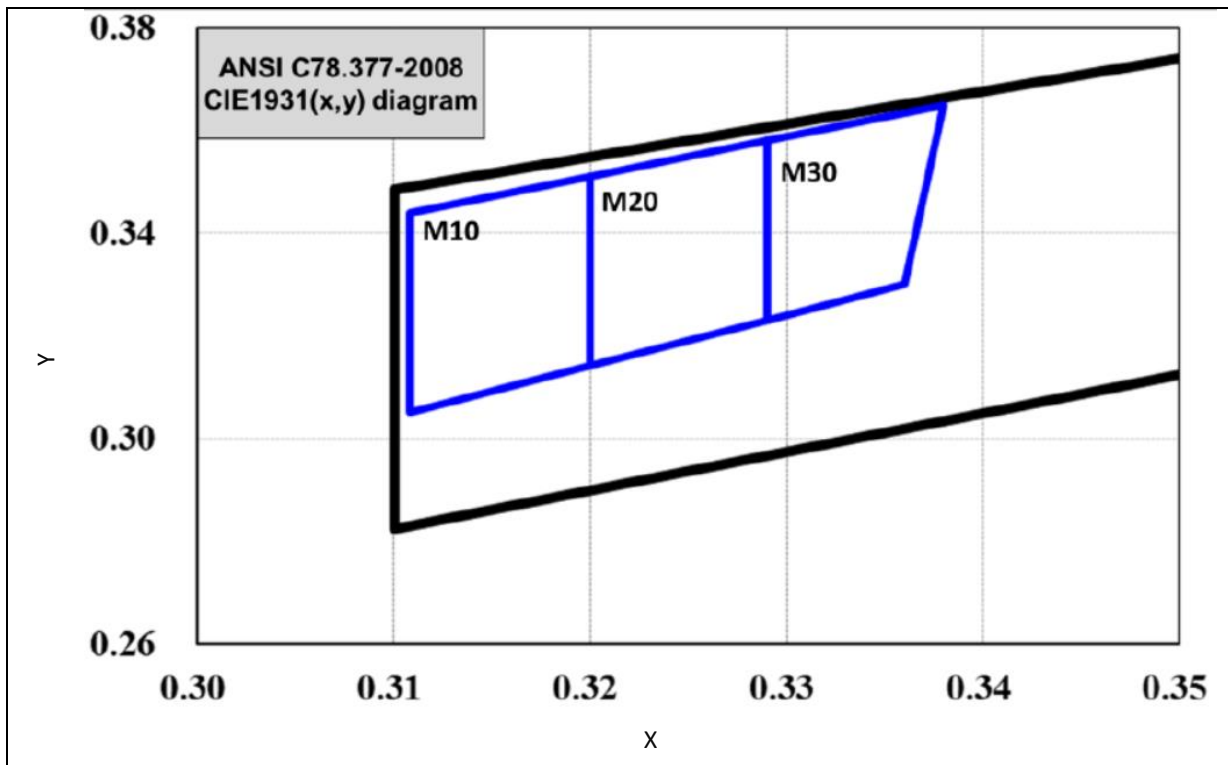
 Luminous Flux Classifications ($I_F = 350\text{mA}$):

Code		Min.	Max.	Unit
Cool White	DE	140	150	lm
	DF	150	160	
	DG	160	170	
	DH	170	180	
Blue	3	30	40	lm
	4	40	50	
	5	50	60	

 Dominant Wavelength (Blue) Classifications ($I_F = 700\text{mA}$):

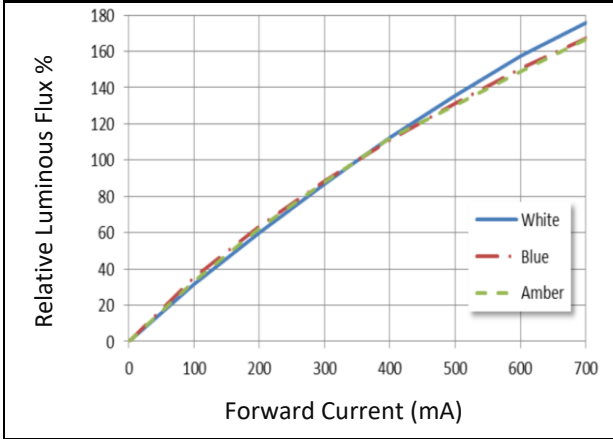
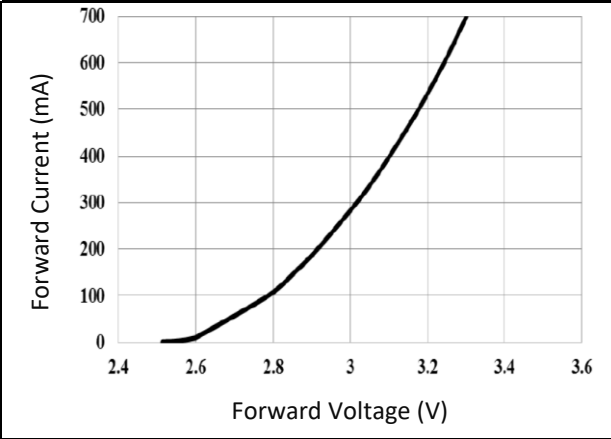
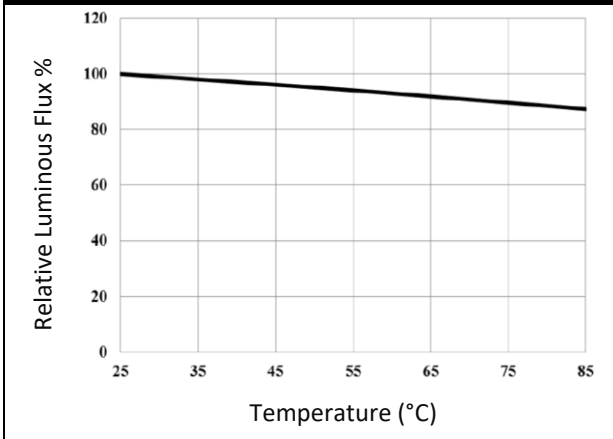
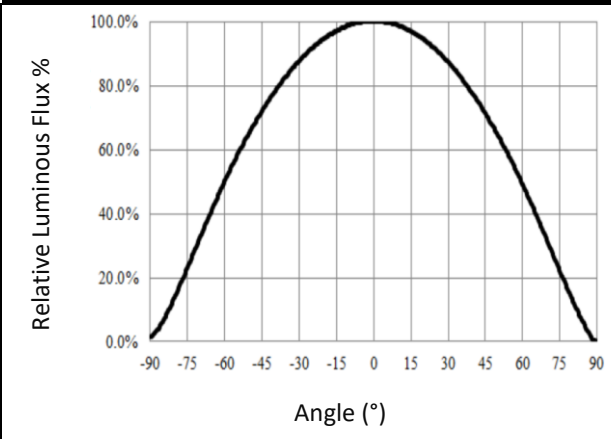
Code	Min.	Max.	Unit
460	460	465	nm
465	465	470	

CIE CHROMATICITY DIAGRAM (Cool White):



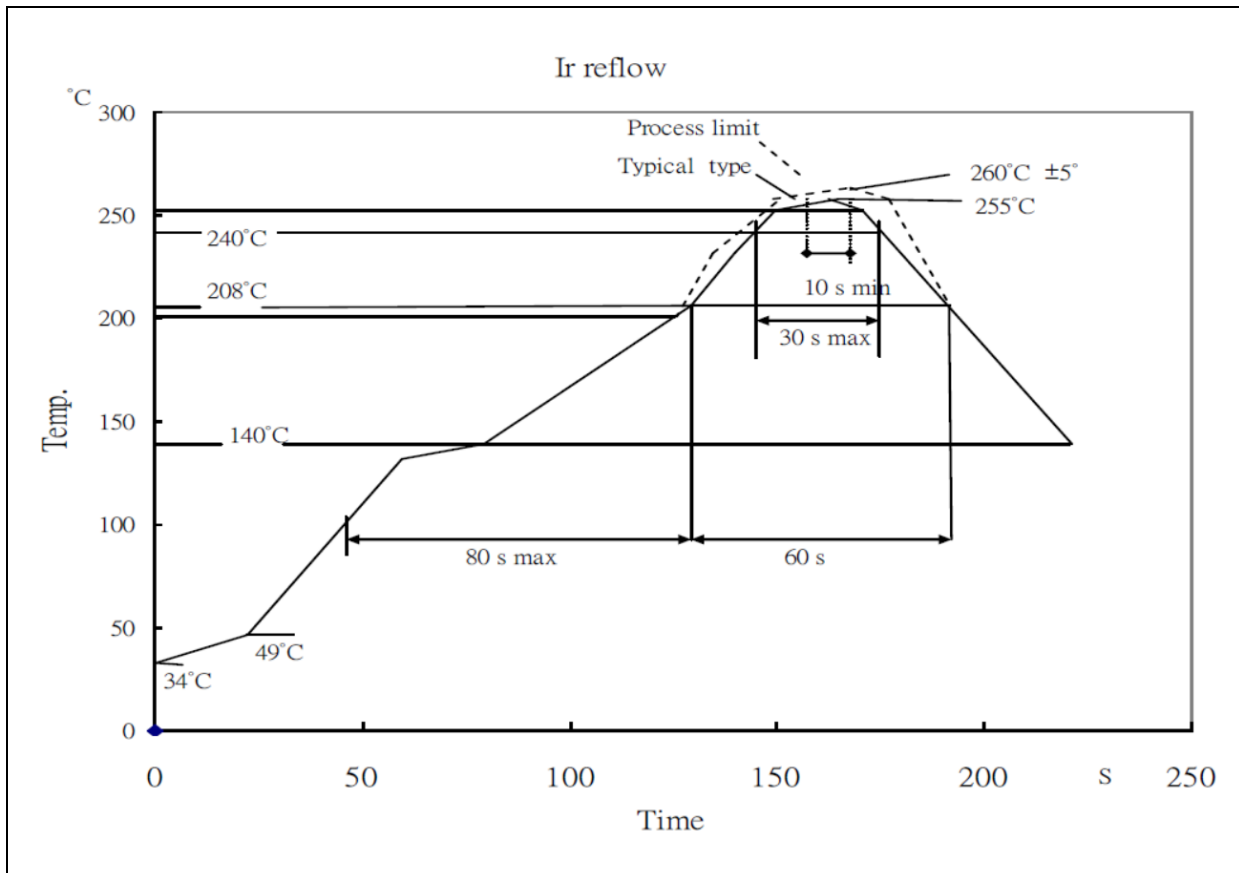
Chromaticity Coordinates Classifications ($I_F = 350\text{mA}$):

	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
M10	0.3200	0.3511	0.3108	0.3440	0.3108	0.3050	0.3200	0.3141
M20	0.3200	0.3511	0.3290	0.3581	0.3290	0.3231	0.3200	0.3141
M30	0.3290	0.3581	0.3380	0.3650	0.3360	0.3300	0.3290	0.3231

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Luminous Flux v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Flux v.s. Temperature

Directive Radiation


RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:

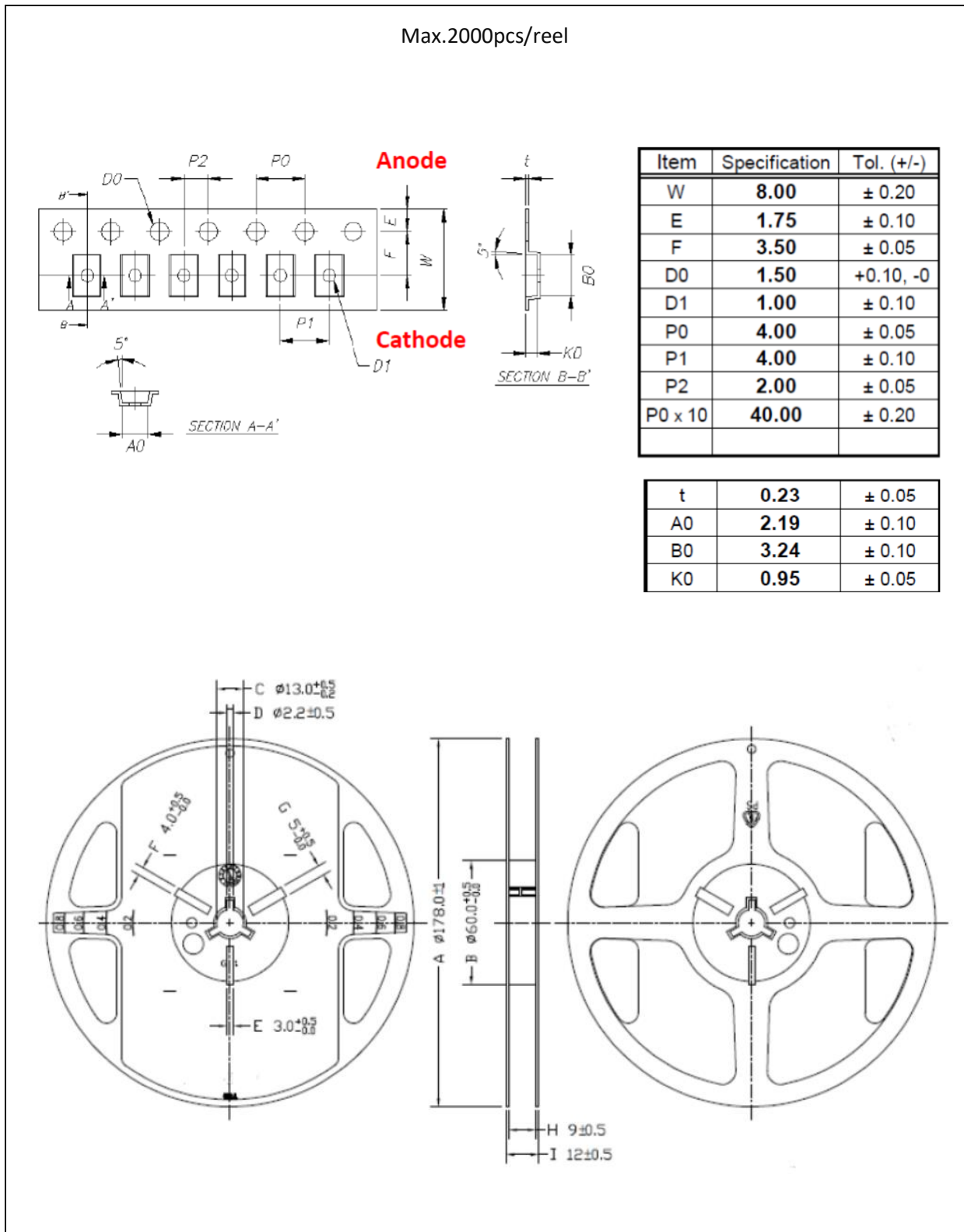


Note:

1. Maxima reflow soldering: 1 time.
2. The recommended reflow temperature is 240°C. The maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	12/07/2021	Datasheet set-up.
A1.1	25/11/2021	Update typ. lumen value.